



New Generation of Rad-Hard SoC FPGA

CERN SoC Workshop

Rad-hard FPGA Offering

Complete rad-hard FPGA offering and associated tools

- NX offers a complete rad-hard FPGA offering with all associated tools
- IMPULSE is the programming tools that generate any VHDL into bistream generation
- All required tools ecosystem and IPs to develop simple to complex design



 medium

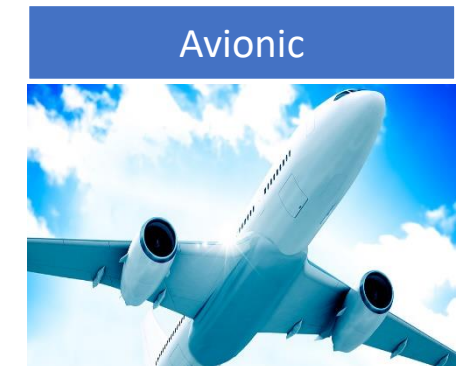
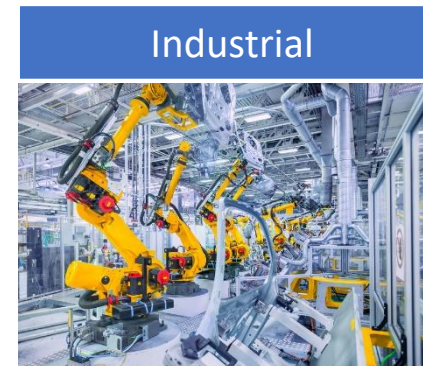
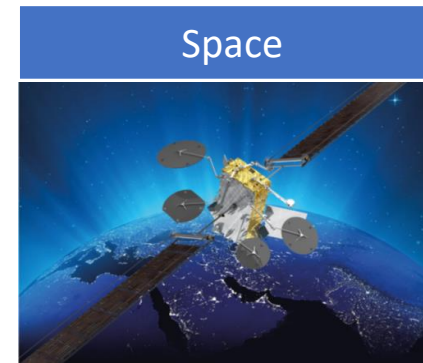
 ultra 300

 large

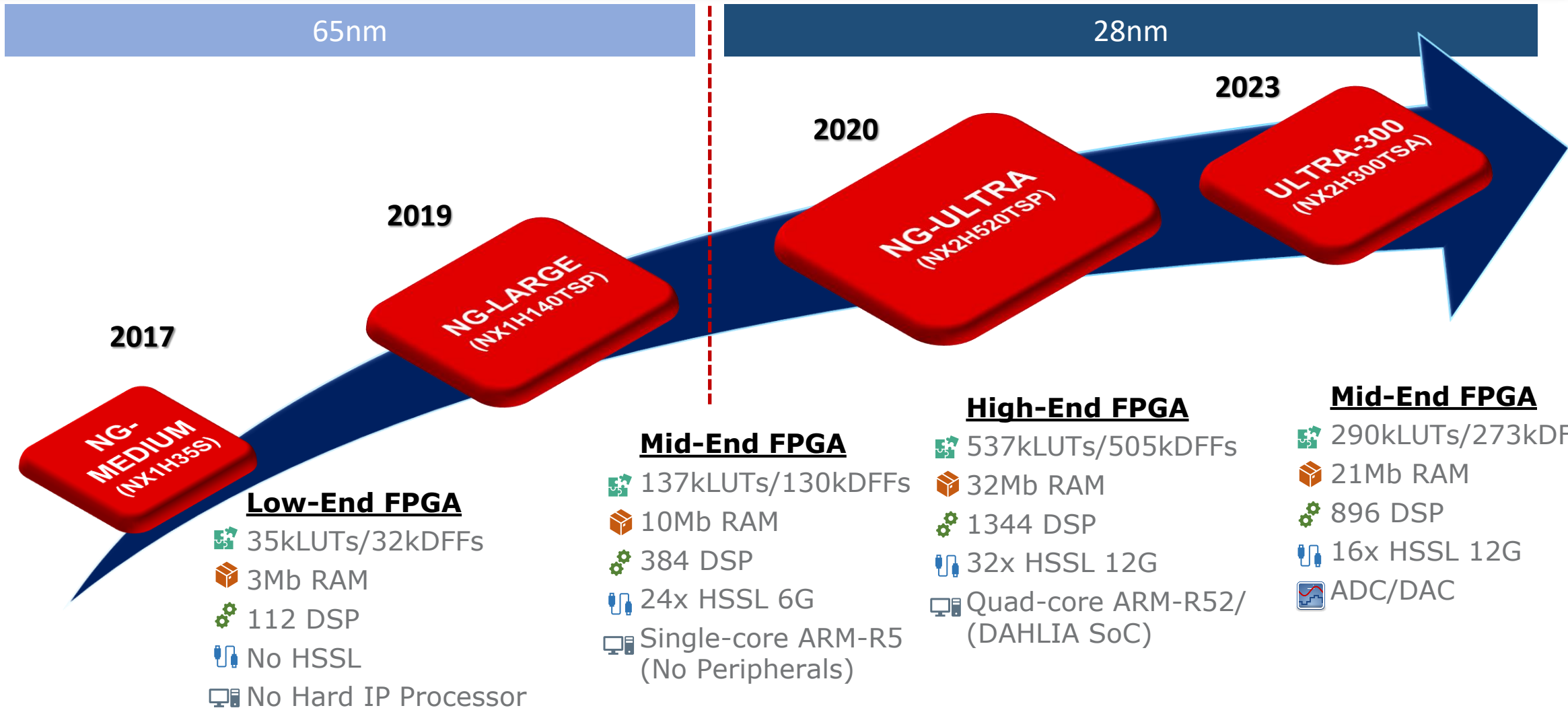
 ultra

Key Markets

- The company is focusing on developing SoC FPGA for Hi-Rel markets
- Become quickly a clear leader on Space, Defense and Avionic market
- Focus on key market differentiators like radiation hardening, very high reliability, ITAR free etc



Rad-Hard SoC FPGA Roadmap



- Low-End FPGA**
- 35kLUTs/32kDFFs
 - 3Mb RAM
 - 112 DSP
 - No HSSL
 - No Hard IP Processor

- Mid-End FPGA**
- 137kLUTs/130kDFFs
 - 10Mb RAM
 - 384 DSP
 - 24x HSSL 6G
 - Single-core ARM-R5 (No Peripherals)

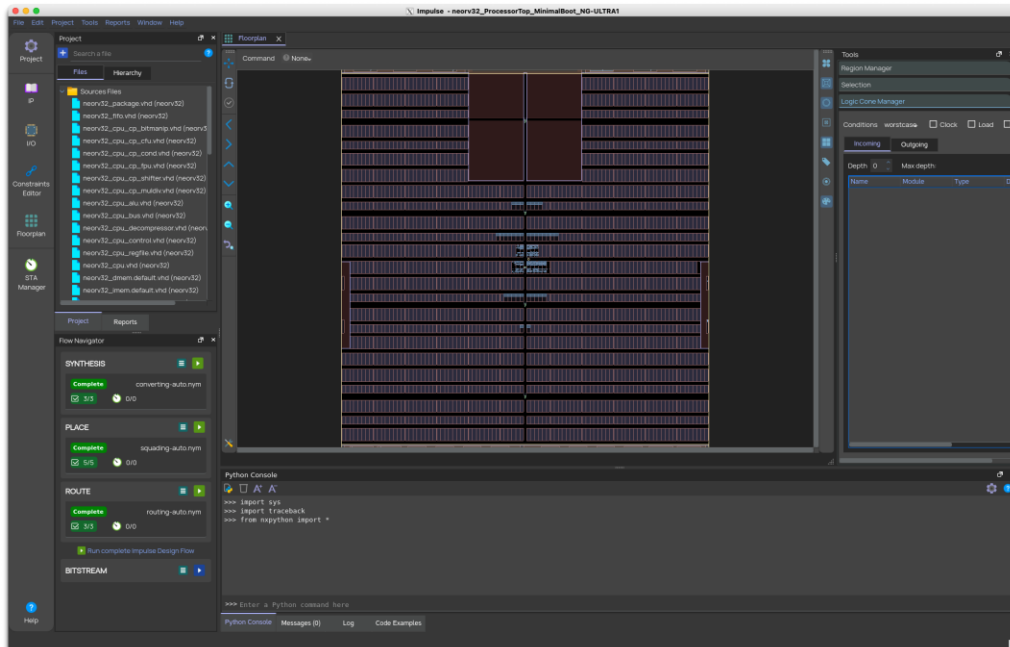
- High-End FPGA**
- 537kLUTs/505kDFFs
 - 32Mb RAM
 - 1344 DSP
 - 32x HSSL 12G
 - Quad-core ARM-R52/ (DAHLIA SoC)

- Mid-End FPGA**
- 290kLUTs/273kDFFs
 - 21Mb RAM
 - 896 DSP
 - 16x HSSL 12G
 - ADC/DAC

Software Tools Overview

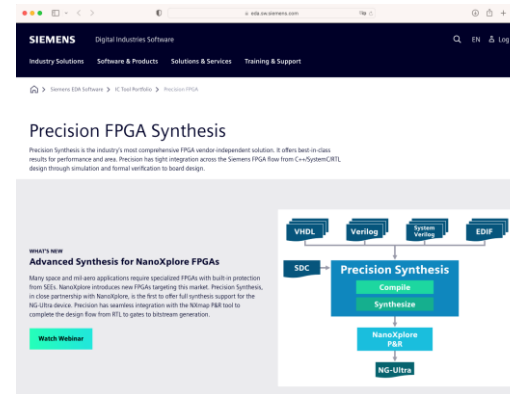
NanoXplore's toolset: Impulse

- Performs all stages of the design, thus NanoXplore is independent from any third party tool



NanoXplore's toolset: 3rd party tools

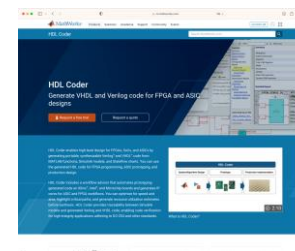
- Precision Hi-Rel (Siemens EDA): NG-ULTRA supported for Synthesis in the commercial releases



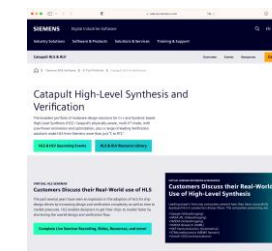
MBSE ecosystem/ HLS :


- First support available
- Further features ongoing

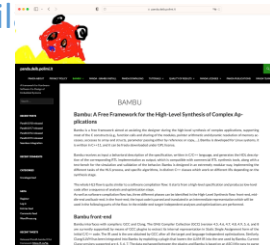
 HDL Coder Mathworks:



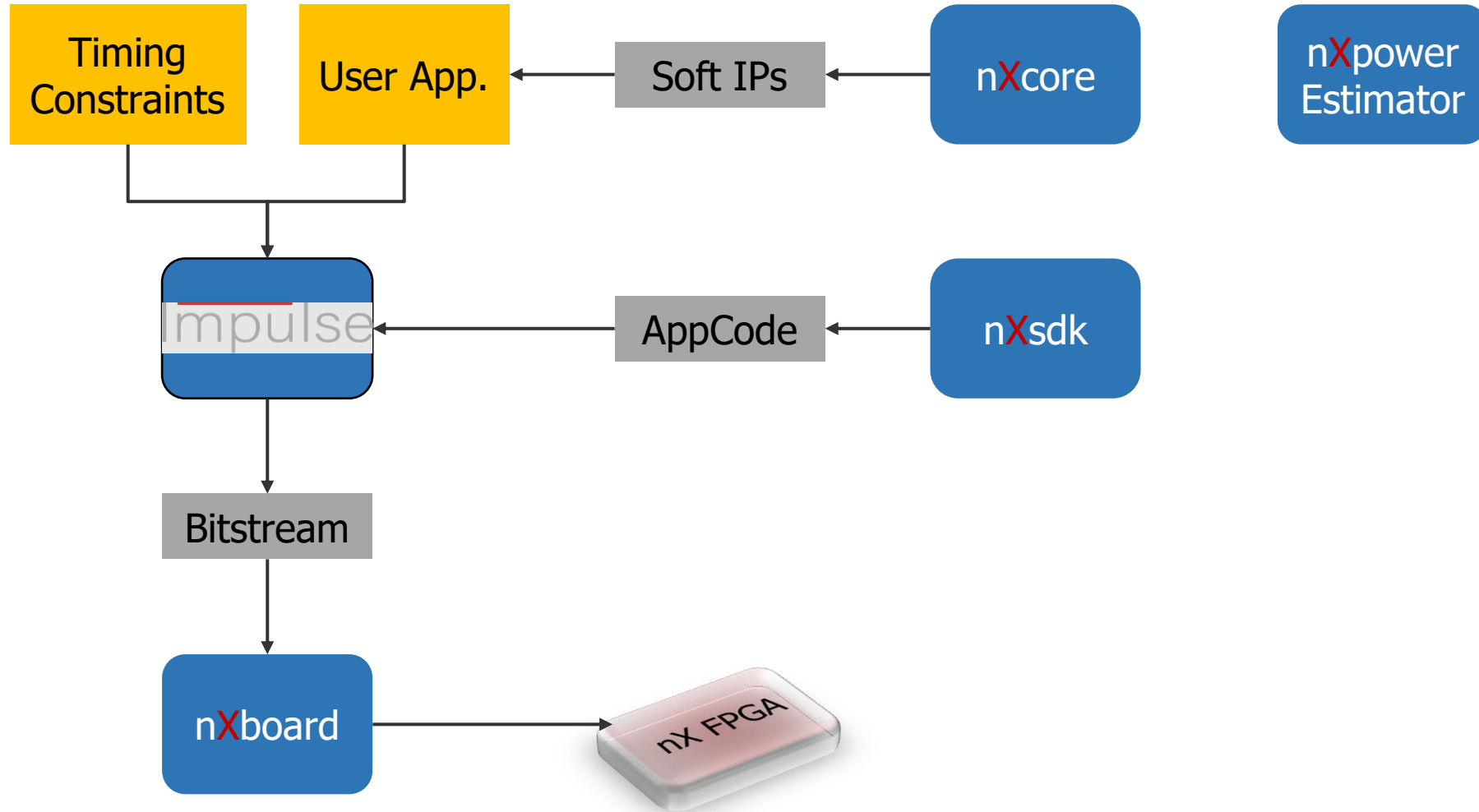
 CatapultC Siemens ESA:



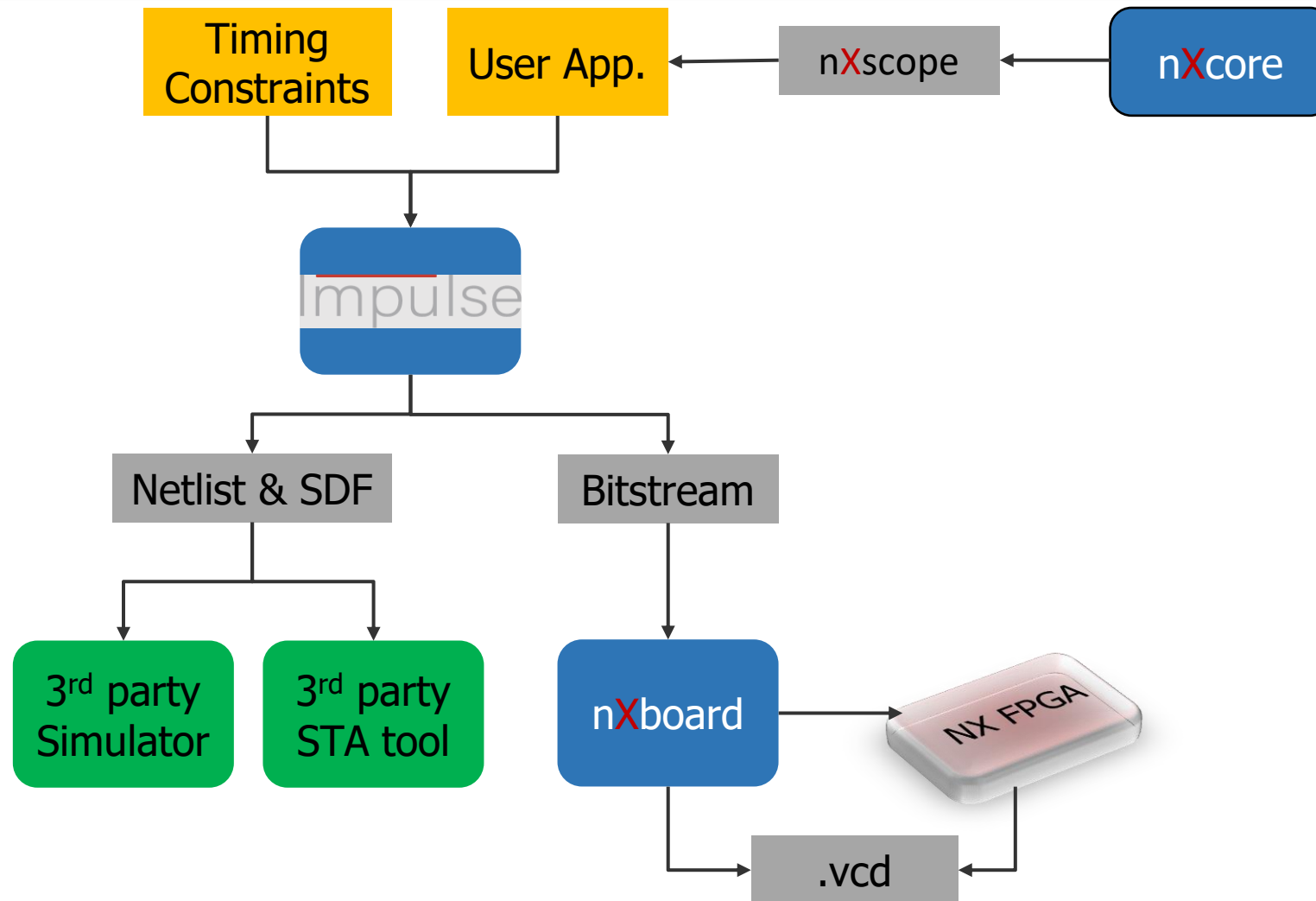
 Bambu, Politecnico di Mil.



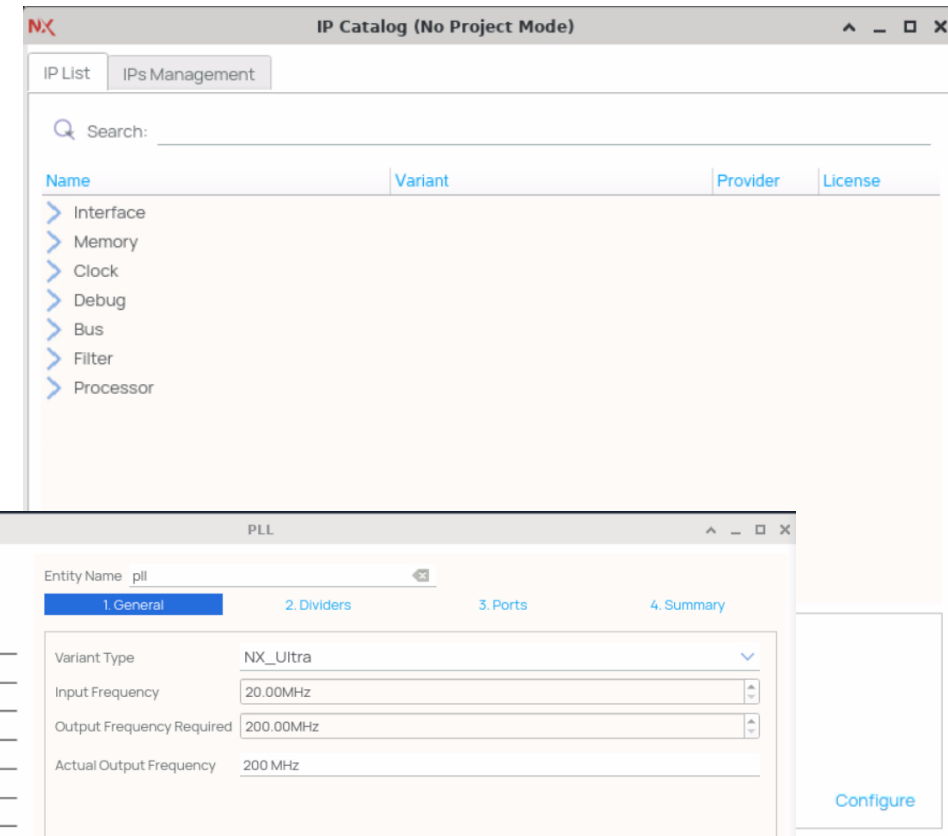
Software Tools Flow



Software Tools Debugg

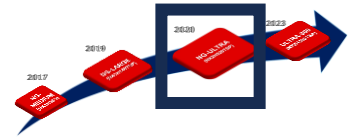
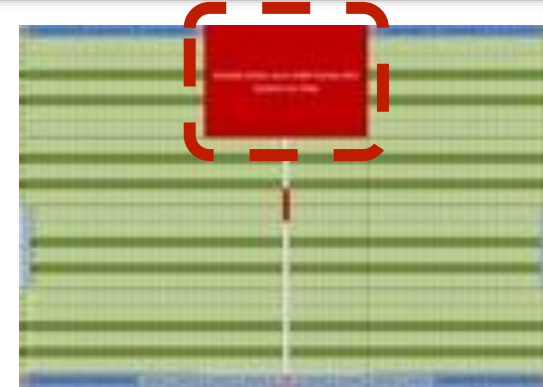
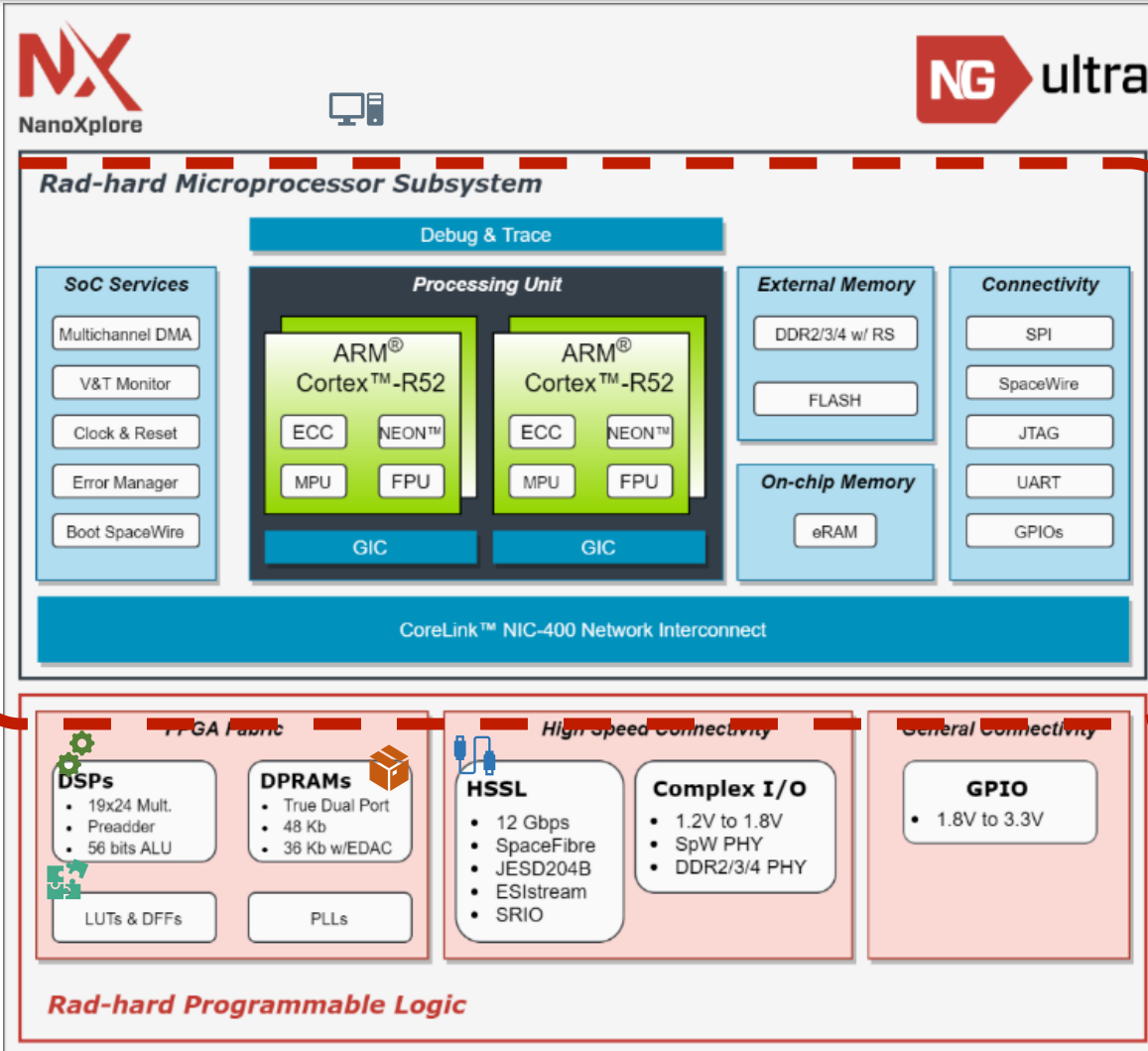


- nXcore is directly available in IMPULSE to import any available IPs
- DDR2 Controller
- Infrastructure IPs
- Filters
- Softcore
 - Leon3
 - RISC V (Q1 2024)
- HSSL protocols



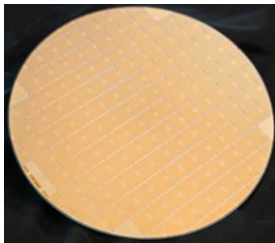


NG-ULTRA Overview



- Rad-Hardened By Design SRAM-based SoC FPGA
- Quadcore ARM R52 @ 600MHz each
- 537 KLUT density
- SpW & DDR 3&4 PHY hard-coded
- 32 HSSL @ 12 Gbps, compatible with:
 - SpaceFibre, JESD204B, ESistream, SRIO
- BGA 1752 package

NG-ULTRA Supply Chain



- **Fab:** ST Crolles
28nm FD-SOI



- **Assembly flip chip**
- ST Rennes



- **Testing**
- ST Grenoble

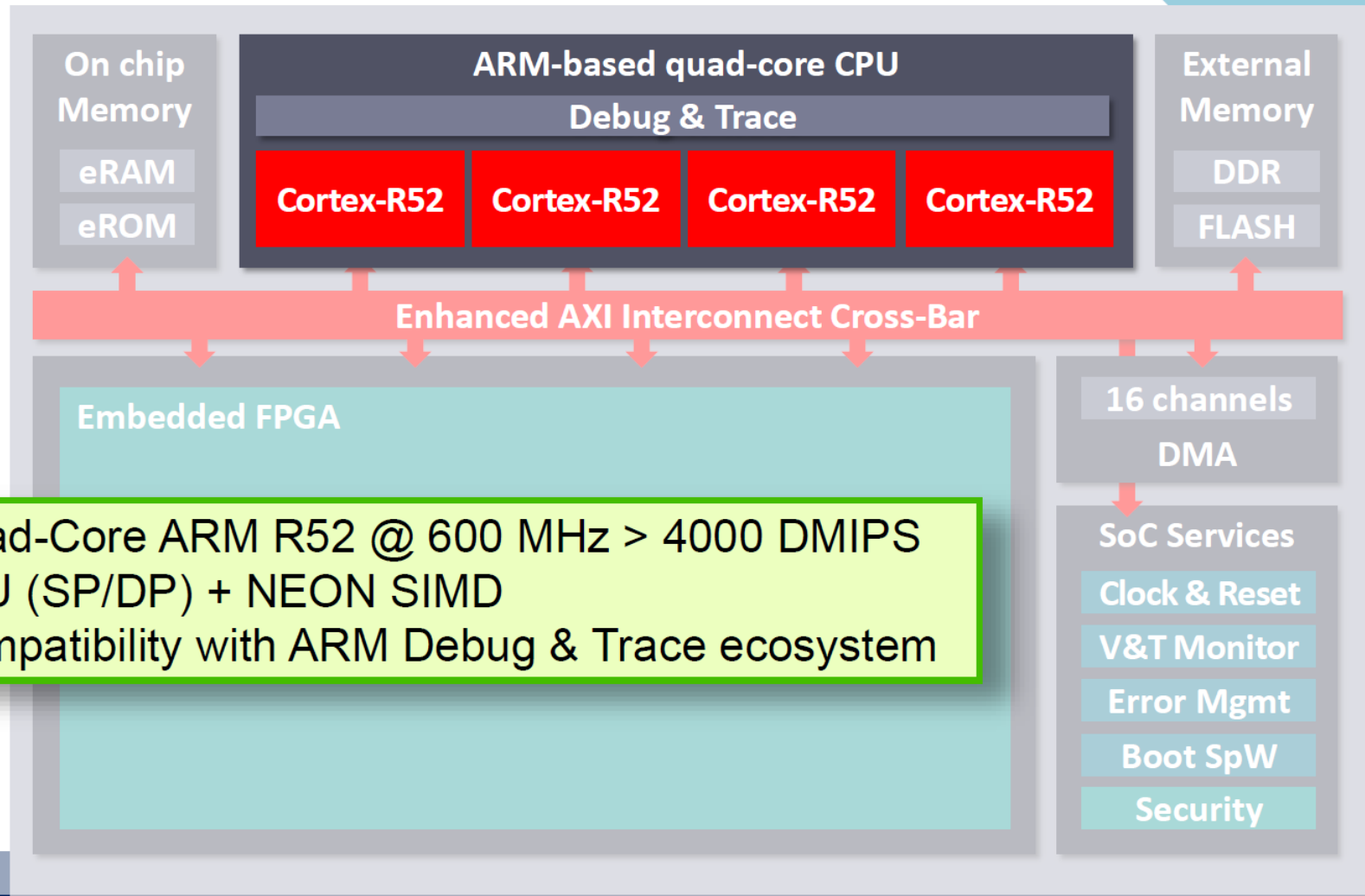
✓ **Fully European supply chain !**

NG-ULTRA Overview

Device	NG-ULTRA
Capacity of modules	
Register	505 344
LUT-4	536 928
Carry	126 336
Embedded RAM	
Core RAM Blocks (48K-bit)	672
Core RAM Bits (K = 1024)	32 256 K
Core Register File Blocks (32 x 18-bit)	2 632
Core Register File Bits	1 480 K
Embedded DSP	
	1 344
Clocks	
	50
Embedded Serial Link	
HSSL 12,5 Gbps, SERDES TX/RX (Supports several protocols including Space Fibre)	32
SpaceWire with codec 400Mbps	1
I/Os	
I/O Complex Banks	10 (34 I/Os per bank)
I/O Direct Banks	4 (24 I/Os per bank)
I/O Service Bank	1 (44 I/Os)
I/O DDR Bank	1 (204 I/Os)
I/O BScan Banks	2 (28 I/Os per bank)
User I/Os	740
I/O PHYSICAL INTERFACES	
DDR/DDR2/DDR3	20
SpaceWire	20

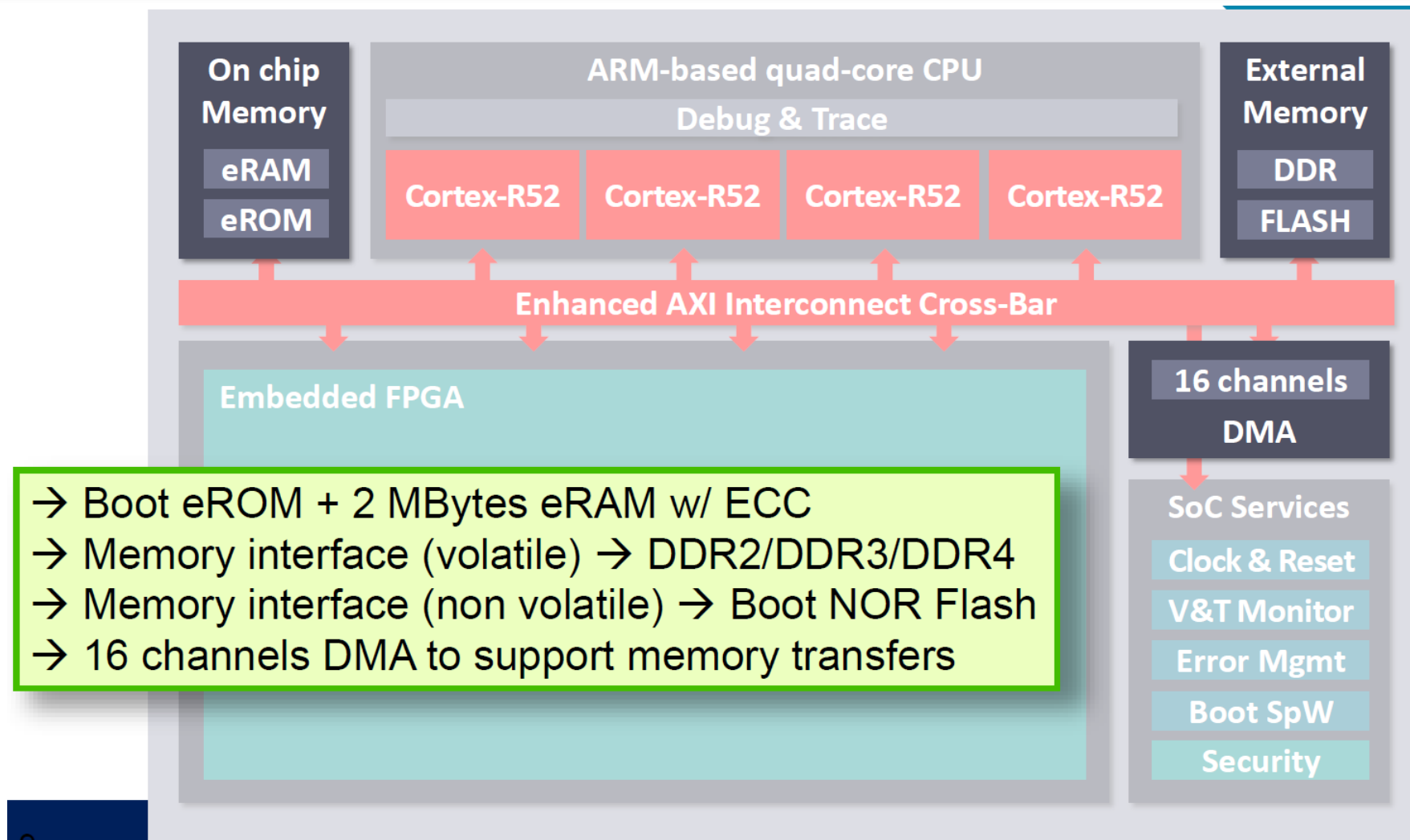


NG-ULTRA Overview



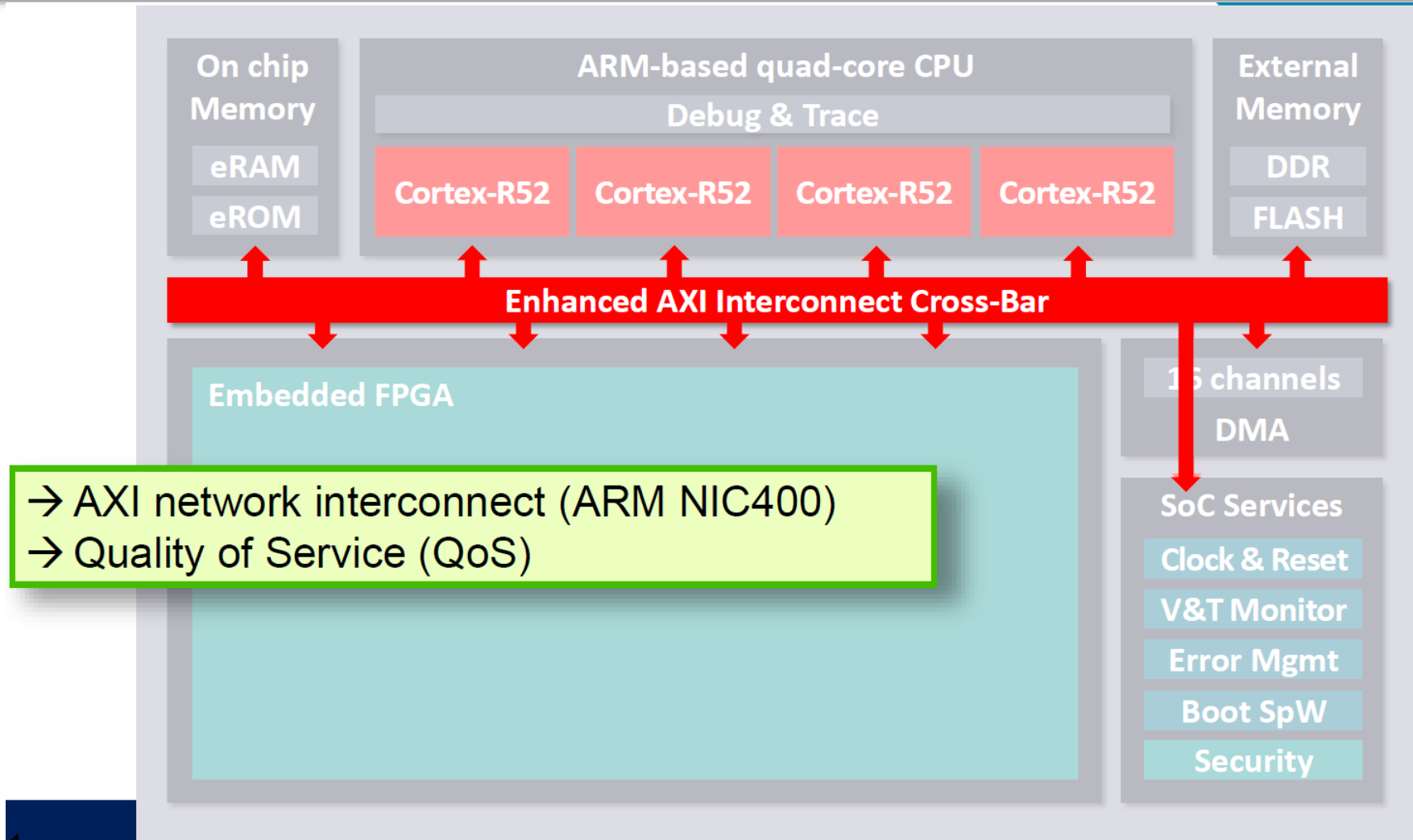
- Quad-Core ARM R52 @ 600 MHz > 4000 DMIPS
- FPU (SP/DP) + NEON SIMD
- Compatibility with ARM Debug & Trace ecosystem

NG-ULTRA Overview



- Boot eROM + 2 MBytes eRAM w/ ECC
- Memory interface (volatile) → DDR2/DDR3/DDR4
- Memory interface (non volatile) → Boot NOR Flash
- 16 channels DMA to support memory transfers

NG-ULTRA Overview



- Generic build system for embedded software
 - Including Makefiles and generation instructions
 - Generic linker script
 - Ready to use drivers
 - Flash, Clock & Reset, DMA, DDR, UART, eRAM, GIC...
 - ARM R52 init (crt0, handler, MPUs, stack...)
 - HAL and Helpers
 - Example applications & demo
- Easy to use

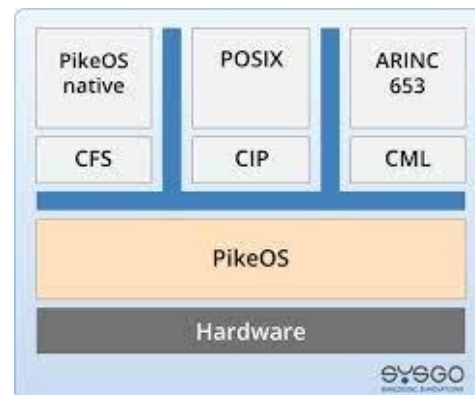
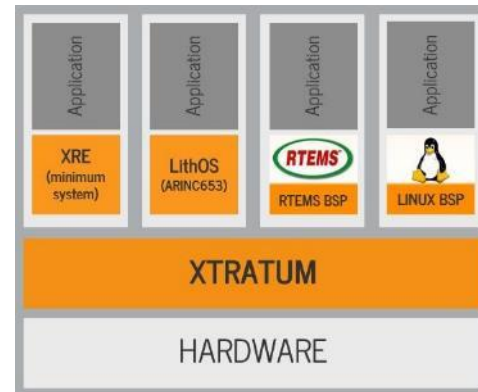
- ✓ Debugging facilities:
 - Lauterbach (debug & trace)
 - OpenOCD support
- ✓ Flash programmer
- ✓ Bitstream loader
- ✓ Memory dumper using DAP (debug access port)
- ✓ BL1 signer
- ✓ Read temperature sensor



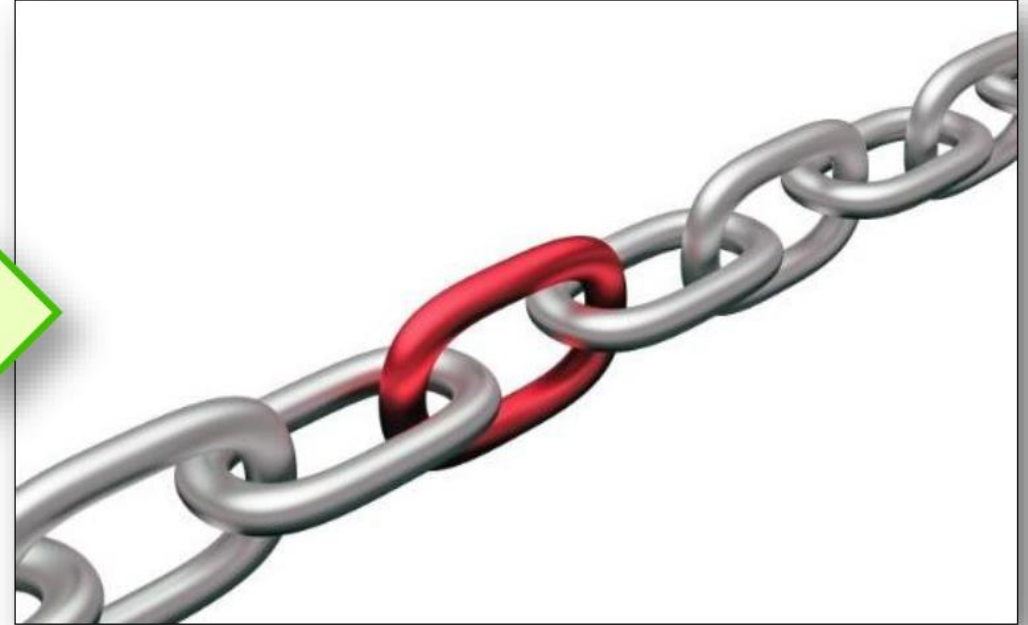
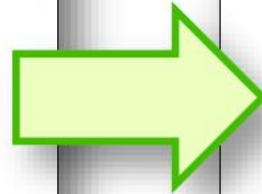
➤ More on the way...

OS Supports

For NG-ULTRA



Radiation Performance – No Weakest Link (1)



Having a high performance and very robust component is not enough, because if it is associated to sensitive components (such as peripheral memories), the overall robustness will depend on the “weakest link”.
As an example, if you need to reboot each time you have an upset in a memory, this will drive the way you operate your processing module... this is an issue...

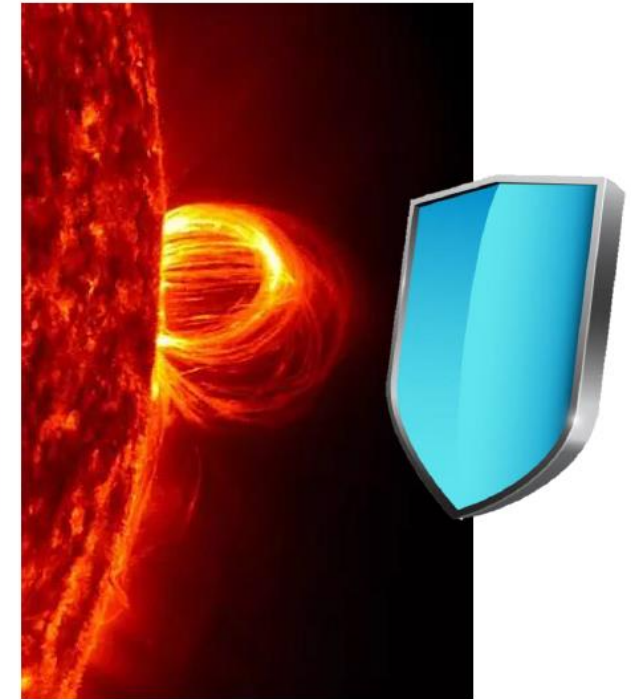
NG-Ultra solves this issue, since (1) it offers a robust Radiation Hardened By Design (RHBD) chip and (2) it provides unprecedented protection mechanisms for all of its peripheral components (Flash, DDR) allowing to use it without risk of introducing a “weakest link”.

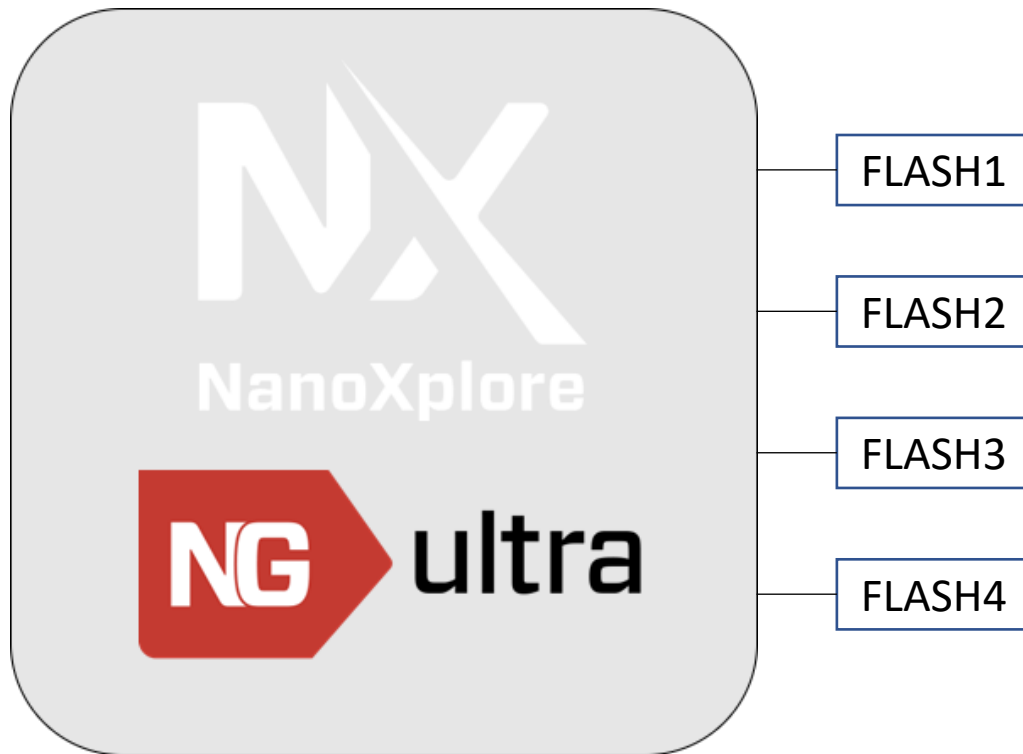
NG-Ultra radiation robustness is... impressive !

- 28FDSOI technology intrinsically latch-up immune → **no SEL**
- NG-Ultra tested during 2 radiation campaigns → **no SEFI**
- Robustness confirmed (**no SEU, no SEFI**) on v1, v2 launched

DDR memory protection → a game changer

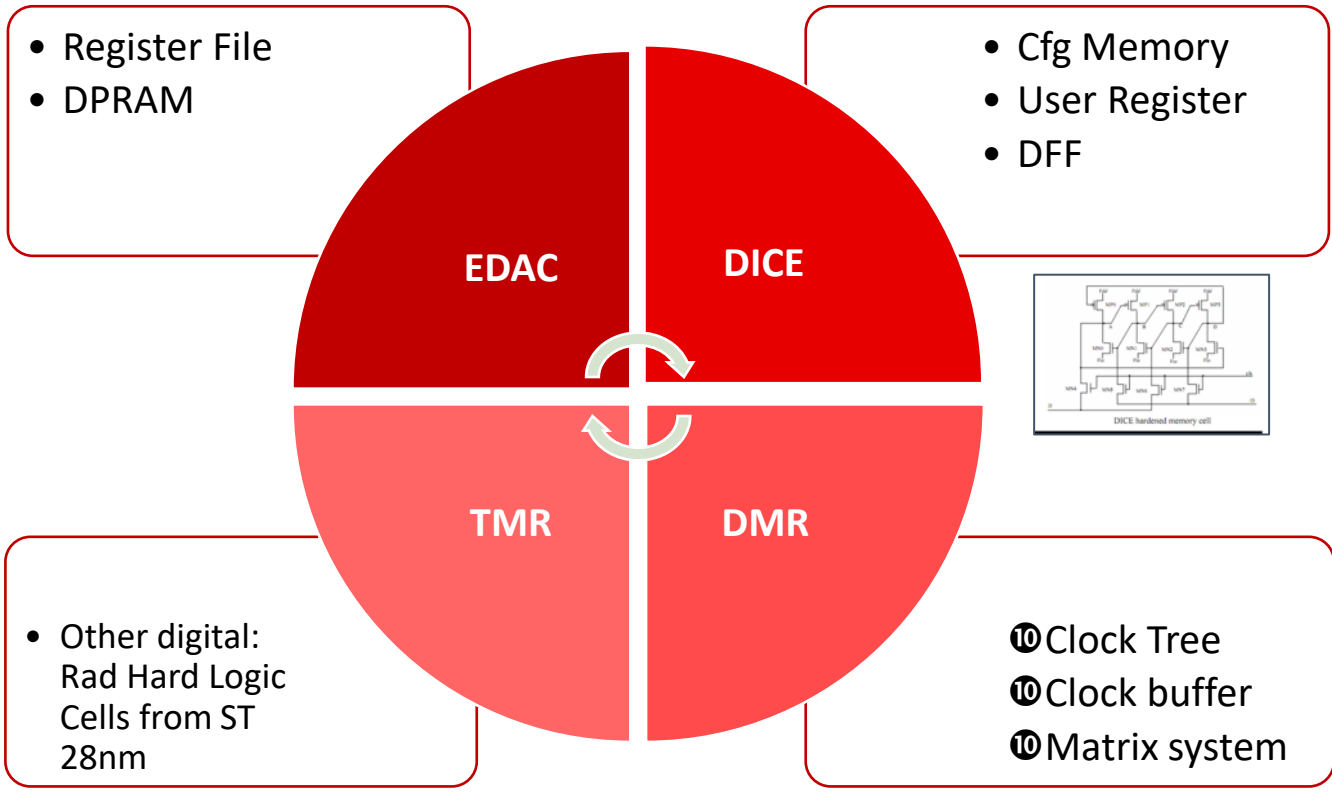
- Supporting DDR2, DDR3 and **DDR4** / 8-bits & 16-bits devices
- Reed-Solomon for **SEU** high level of memory protection
- **Robustness against SEFI** up to the loss of two 16-bits devices






- 4 parallel SPI interfaces controlled by the boot loader
- FLASH mode:
 - SEQUENTIAL
 - TMR
- Parallel read
- NG-ULTRA performs the majority-voting
- The last memory can be used for an application purpose

28nm radiation hardening approach



 **•Goal**
 No design mitigation techniques required by the FPGA user

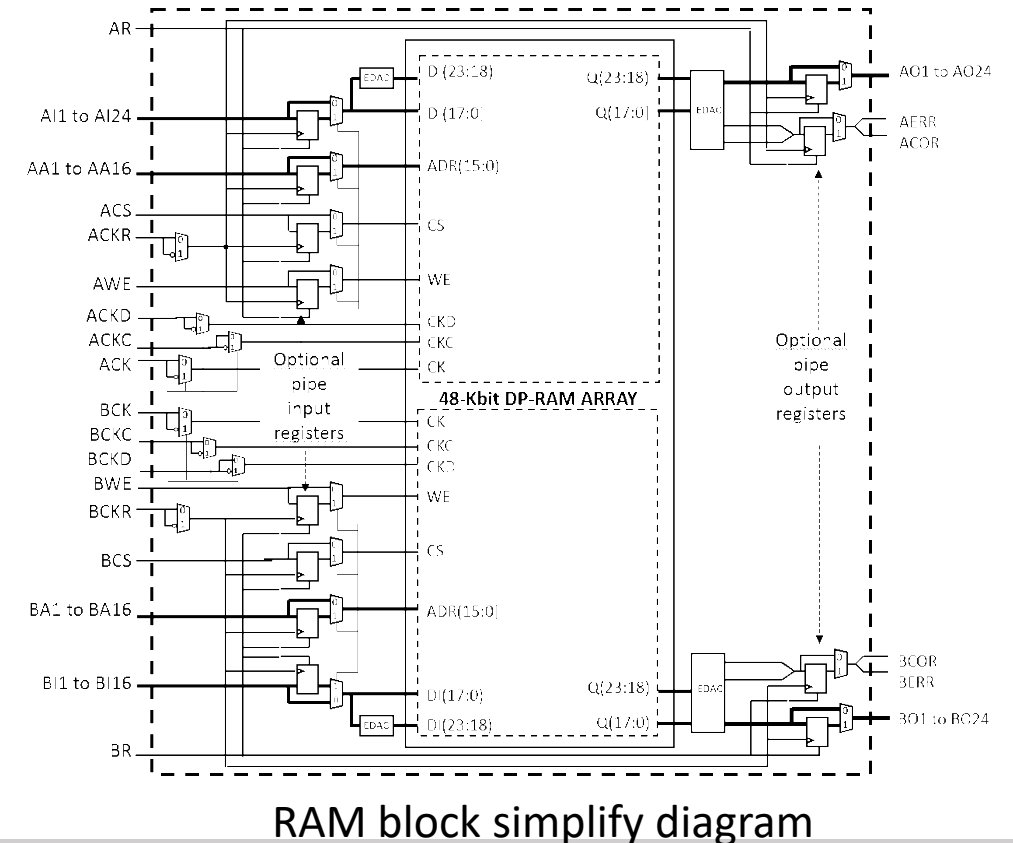
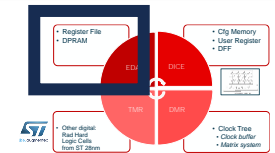
 **Confirmed**
 28nm FD-SOI required less effort to develop the hardened cells compared to 65nm.

In addition, Embedded Configuration Memory Integrity Check (“**CMIC**”)

DPRAM Configurability:


- Optional pipe-line output register
- Initialization by bitstream
- **Embedded SECDEC EDAC**
 - The ECC signature is computed during the write cycle and checked during the read cycle
- **Automatic repair mode**
 - When enabled, the memory is corrected with the data/ ECC value when the correctable error is detected in the read cycle

With EDAC	Without EDAC
2048 x 1-bit	49152 x 1-bit
2048 x 2-bit	24576 x 2-bits
2048 x 6-bit	12288 x 4-bits
2048 x 9-bit	6144 x 8-bits
2048 x 18-bit	4096 x 12-bits
	2048 x 24-bits




Radiation test sessions overview

NG-ULTRA FPGA Radiation test campaigns overview

- 2019
- 
- UCLouvain / HIF (BE)
DEMETER
Test chips



- 2020 2021
- 
- UCLouvain / HIF (BE)

NG-ULTRA V1
1st prototypes



Parts thickness: 50, 70 μm
Tilt and roll possible

- 2023 2023 2023
- 
- RADEF Jyväskylä (FI)

NG-ULTRA V2
final



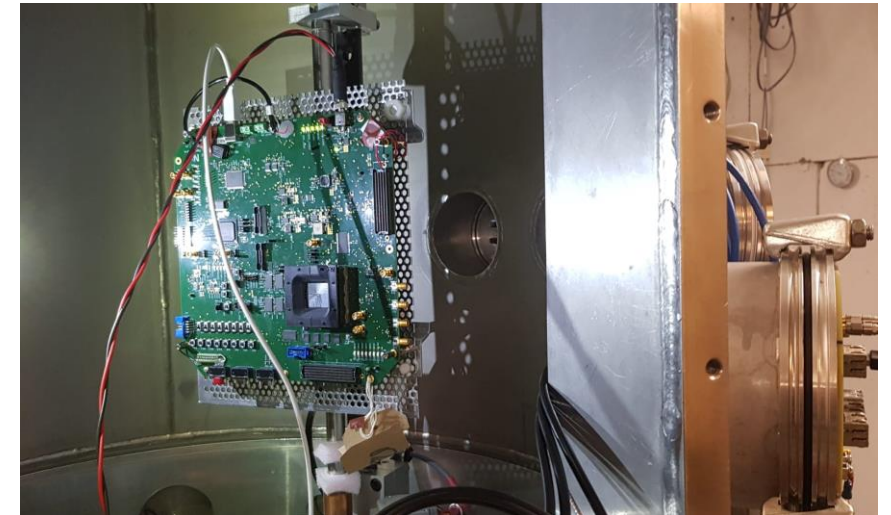
Parts thickness: 100 μm
Tilt and roll not possible
or high energies

Summary of the Configuration Memory (CMEM) test

- Test campaign: RADEF April-2023
- Number of bit in the configuration memory: **90.834.656**
- Bits Location: distributed in the whole chip
- Test Configuration:
 - Bitstream with Checkerboard (0101.....01)
 - CMIC (internal scrubber) : disabled
 - Voltage VDD_CORE -5% // nominal,
 - runs of 200 sec (shutter controlled, closed during configuration and readback)
- Number of samples: 3
- Flux: 5K ions/cm²/s
- Fluence reached : 1E+07 ions/cm²

0 errors in CMEM up to LET 62 MeV*cm²

✓ Result consistent with the previous radiation test campaigns.

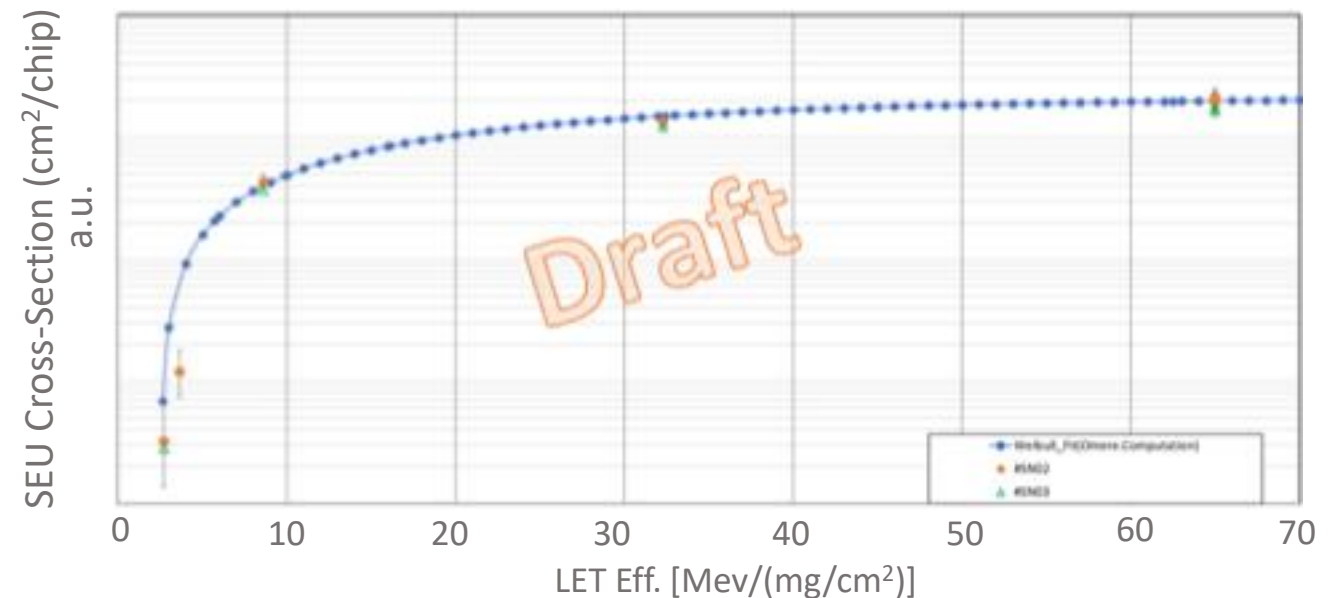


Summary of the DPRAM test

- Test campaign: RADEF April-2023
- Number of instances: **88 (672) 12% 4325376 bits**
- Location: 2 rows of each lobe (6 / 5)
- Test Configuration:
 - **Bitstream1** : NOECC_2k x 24
 - **Bitstream2** : FAST_2k x 18
 - Voltage VDD_CORE -5% // nominal
- Number of samples: 2
- Flux: up to 15K ions/cm²/s for bitstream2
- Fluence reached : 1E+07 ions/cm²

No errors were detected using the ECC (even under flux : 15K ions/cm²/s)

⚛ Bitstream1 : NOECC_2k x 24 [3 runs]



✓ Results without ECC consistent with ST radiation data

⚛ Bitstream2 : FAST_2k x 18 [11 runs with ECC enable, 0 run returned error (count by ECC activation)]

Summary of the DFF tests

- Test campaign: RADEF April-2023
- Number of instances: **15k DFF (4%)**
- Bits Location: Lobe R3
- Test Configuration:
 - Bitstream : 15k stages, Window Shift Register (**WSR**)
 - Design frequency: 50 MHz / 80 MHz
 - Voltage VDD_CORE -5% // nominal,
- Number of samples: 2
- Flux: 10K ions/cm²/s
- Fluence reached : 1E+07 ions/cm²

**0 errors detected during the campaign
(up to LET 62 MeV*cm² /mg)**



Radiation test next steps

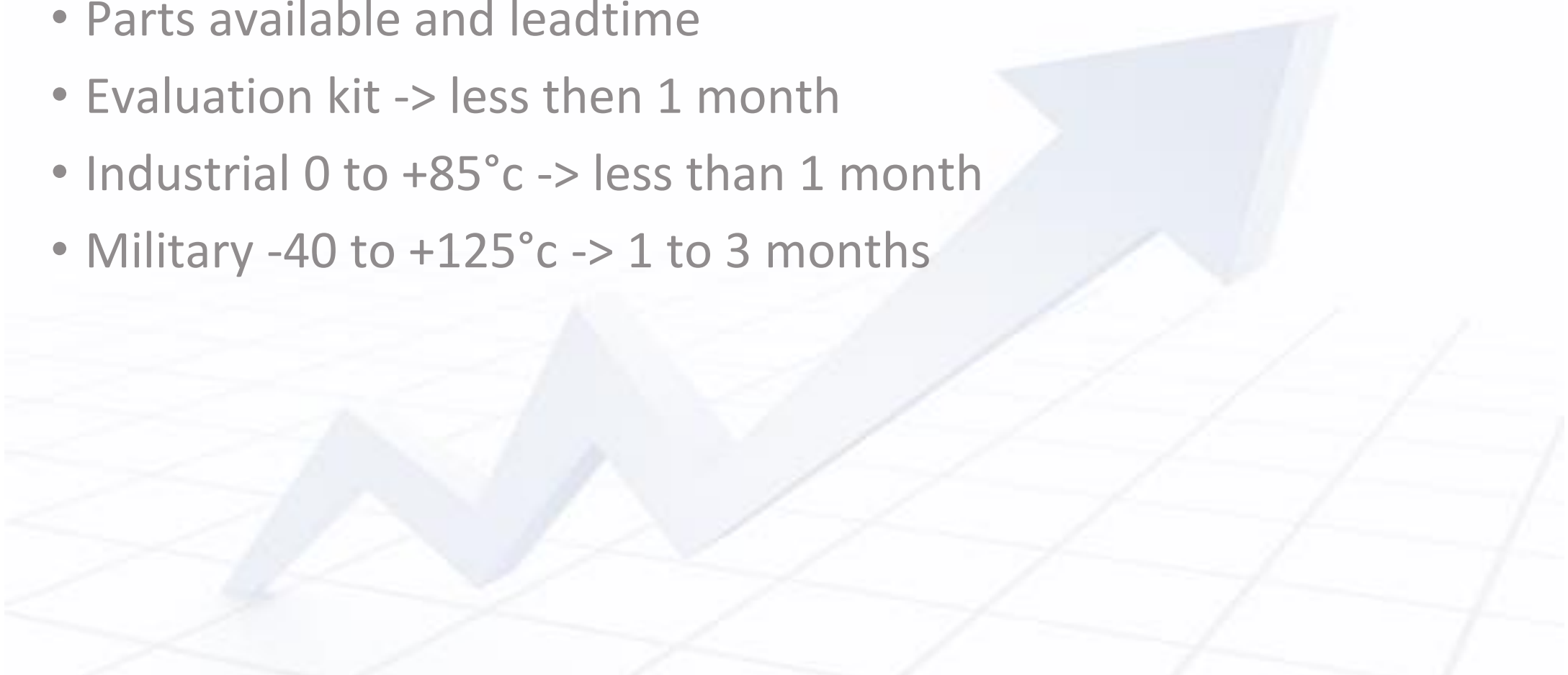
 +1 more HI test session planned Q2 2024 at RADEF Jyväskylä (FI)

 +2 HI sessions planned dedicated to the SoC in 2023 at RADEF Jyväskylä (FI)

 +1 Proton test sessions being planned at PSI in 2024

 **Radiation performances characterized so far are extremely strong !**

Parts available and Leadtime

- Parts available and leadtime
 - Evaluation kit -> less than 1 month
 - Industrial 0 to +85°C -> less than 1 month
 - Military -40 to +125°C -> 1 to 3 months
- 

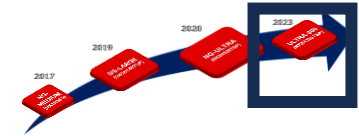
- Illustrative power consumption of NG-ULTRA based on the following design:
- SoC 600MHz
- DFF 107k
- LUT 250k
- RAM 250
- Register file 232
- Clock 50MHz



- Power consumption by rails @Tj 25°C
- 1V SoC dynamic = 1,5W
- 1V Fabric dynamic = 0,7W
- 1V Fabric static = 0,7W
- 1V8 IO = 0,1W
- 3V3 IO = 0,1W
- **Total = 3,1W**

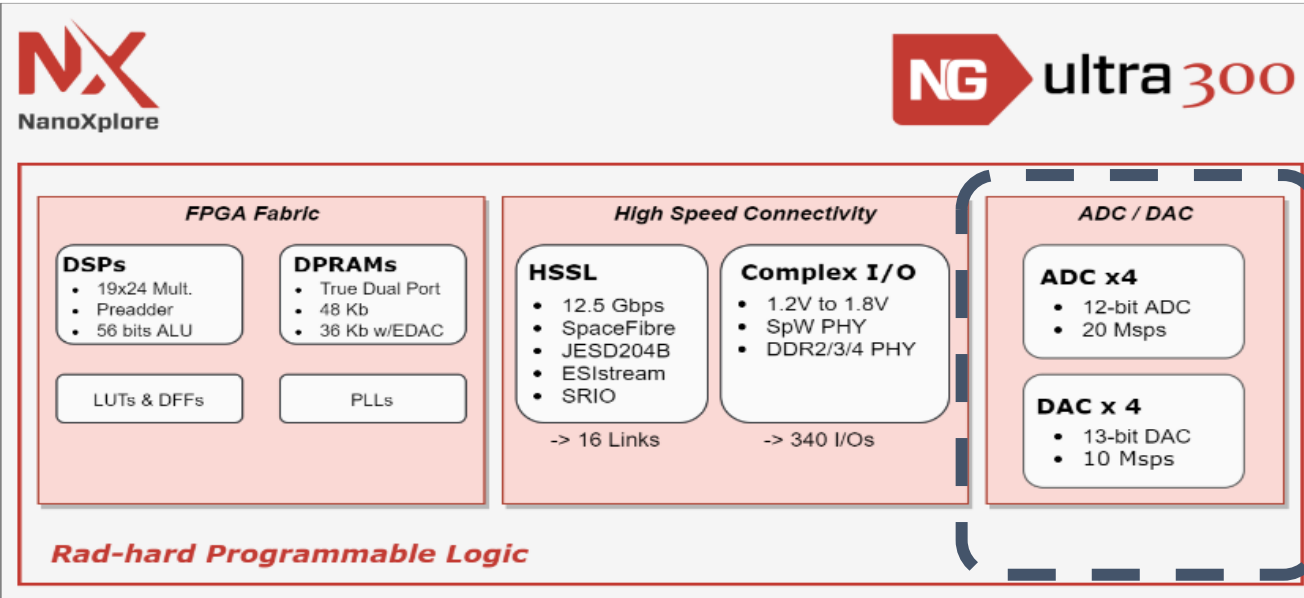


ULTRA 300 Overview

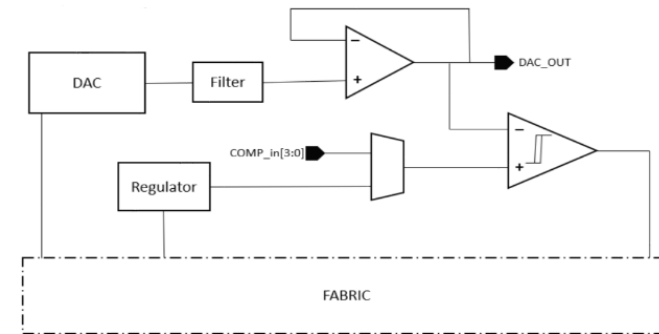


Device		Details	NX2H300TSA	
Capacity - ASIC Gates			4 000 000	
Logic Modules	Rad Hard FPGA	11x Tiles + 7CGBs		
Register		384DFF on 11rows	273 408	
LUT-4		408LUT on 11rows	290 496	
Carry		96CY on 11rows	68 352	
Embedded RAM			22Mb	
DPRAM	Rad Hard SOC	448BRAM * 48Kb	21 504	
Core Register File		On 11 rows	1 424	
Core Register File Bits		32*18bits	807K Hardened	
Clocks / PLL			50 / 6	
Additional Features				
SpaceWire PHY (8 IOBs)	Rad Hard SOC	2x/Complex IOBank	20	
DDR3/4 PHY (11IOBs)		2x/Complex IOBank	20	
DSP Blocks		From 7 rows	896	
SpaceWire link I/F 430Mbps		CODEC	1	
SERDES Tx/Rx 12,5Gbps (supporting several protocols such as Space Fibre)		4 Quad HSSL 12,5Gbps	16	
Hard IP Processor core / SoC			NO	
ADC		12-bit ADC, 10Msps	1	
DAC		13-bit DAC, 10Msps	1	
Design Security				YES
Inputs / Outputs				547 I/Os
Complex I/O bank	I/O	VIO 1,2 – 1,5 – 1,8V	10 x 34 I/Os	
Simple I/O bank		VIO 1,8 – 2,5 – 3,3V	6 x 24 I/Os + 1 x 16 I/Os	
Packages - User I/Os				
FF484 organic	PKG	27*27 mm / 1 mm	239 I/Os (TBC)	
FF1152 organic		35*35 mm / 1 mm	547 I/Os (TBC)	

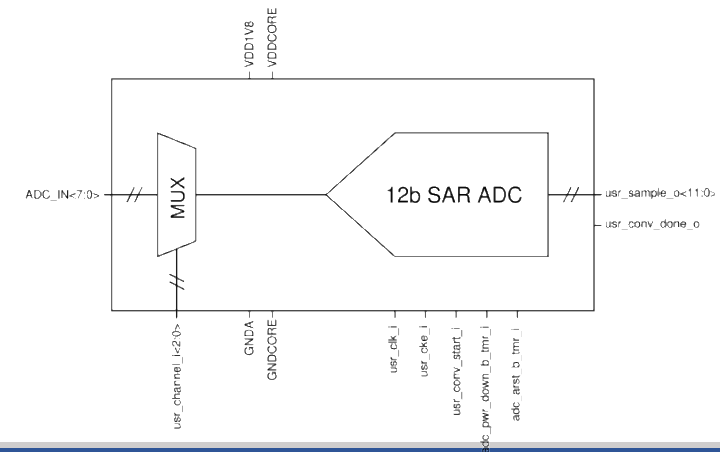
- 290 KLUT density
- 16 HSSL @ 12 Gbps, compatible with:
 - SpaceFibre, JESD204B, ESStream, SRIO
- ADC and DAC
- BGA 484 and BGA 1152 package



13-bit DAC, 1-10 MSPS



12-bit ADC, 1-10 MSPS up to 8 inputs

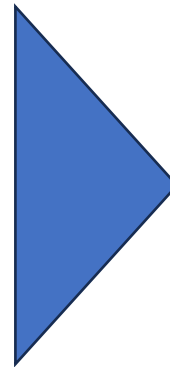


🌀 2 HI test session planned in 2024 at RADEF Jyväskylä (FI)

🌀 +1 Proton test sessions being planned at PSI in 2024

✓ **Same blocks as NG-ULTRA -> should have the same radiation performance**

- Illustrative power consumption of ULTRA300 based on the following **resource intensive** design:
- DFF 107k
- LUT 250k
- RAM 250
- Register file 232
- Clock 50MHz



- Power consumption by rails @Tj 25°C
- 1V Fabric dynamic = 0,7W
- 1V Fabric static = 0,5W
- 1V8 IO = 0,1W
- 3V3 IO = 0,1W
- **Total = 1,4W**

Parts available and Leadtime

- Parts available and leadtime
- IMPULSE -> now
- Evaluation kit -> Q1 2024
- Industrial 0 to +85°C -> Q1 2024
- Military -40 to +125°C -> Q3 2024

- Any prototyping can be done on NG-ULTRA and then port on ULTRA 300

Customers

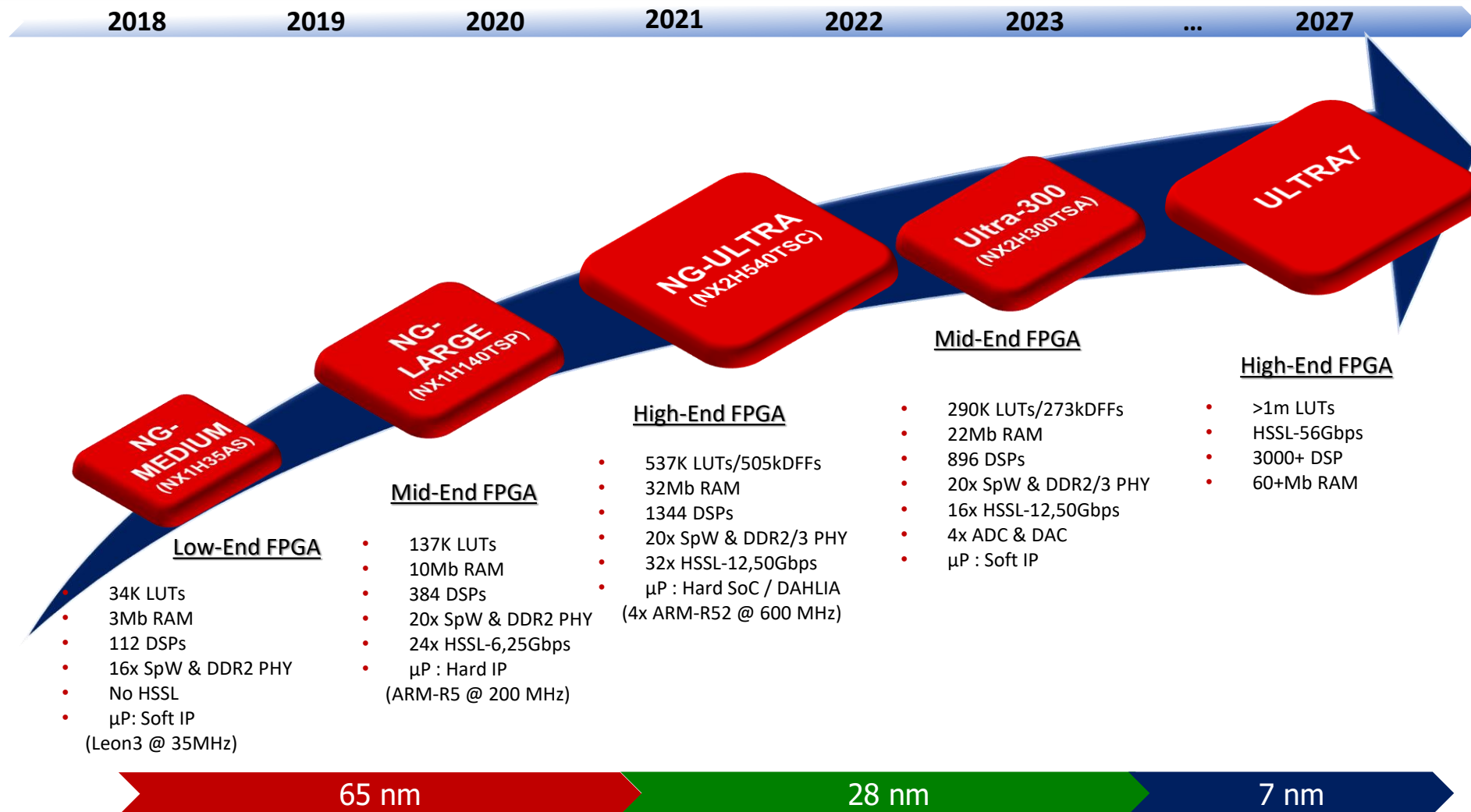


- And others to come

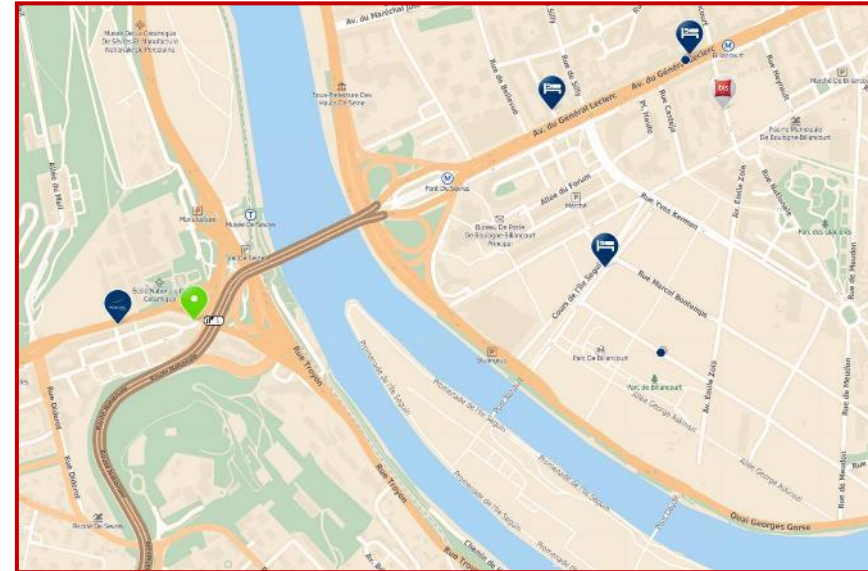


Next?

Rad-Hard FPGA Roadmap



Thank you!



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Documentation:

<https://nanoplore-wiki.atlassian.net>

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